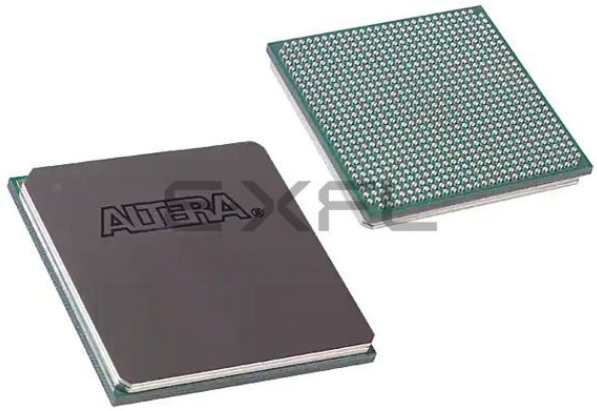

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Details	
Product Status	Active
Number of LABs/CLBs	4713
Number of Logic Elements/Cells	75408
Total RAM Bits	2810880
Number of I/O	426
Number of Gates	-
Voltage - Supply	0.97V ~ 1.03V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	780-BGA
Supplier Device Package	780-FBGA (29x29)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce75f29i8ln

Section II. I/O Interfaces

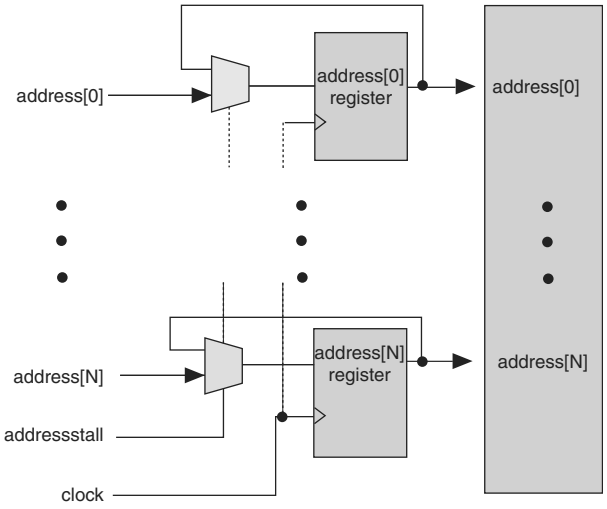
Chapter 6. I/O Features in Cyclone IV Devices

Address Clock Enable Support

Cyclone IV devices M9K memory blocks support an active-low address clock enable, which holds the previous address value for as long as the `addressstall` signal is high (`addressstall = '1'`). When you configure M9K memory blocks in dual-port mode, each port has its own independent address clock enable.

Figure 3–2 shows an address clock enable block diagram. The address register output feeds back to its input using a multiplexer. The multiplexer output is selected by the address clock enable (`addressstall`) signal.

Figure 3–2. Cyclone IV Devices Address Clock Enable Block Diagram



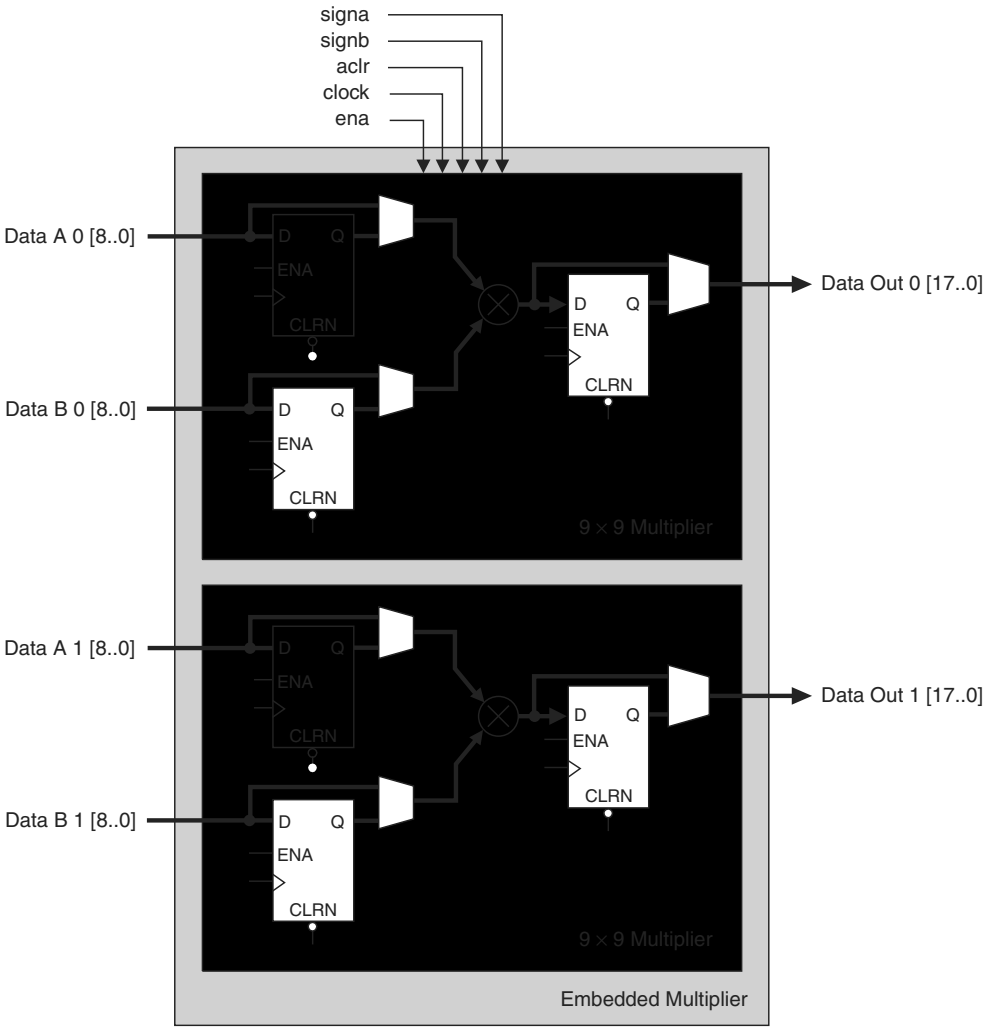
The address clock enable is typically used to improve the effectiveness of cache memory applications during a cache-miss. The default value for the address clock enable signals is low.

9-Bit Multipliers

You can configure each embedded multiplier to support two 9 × 9 independent multipliers for input widths of up to 9 bits.

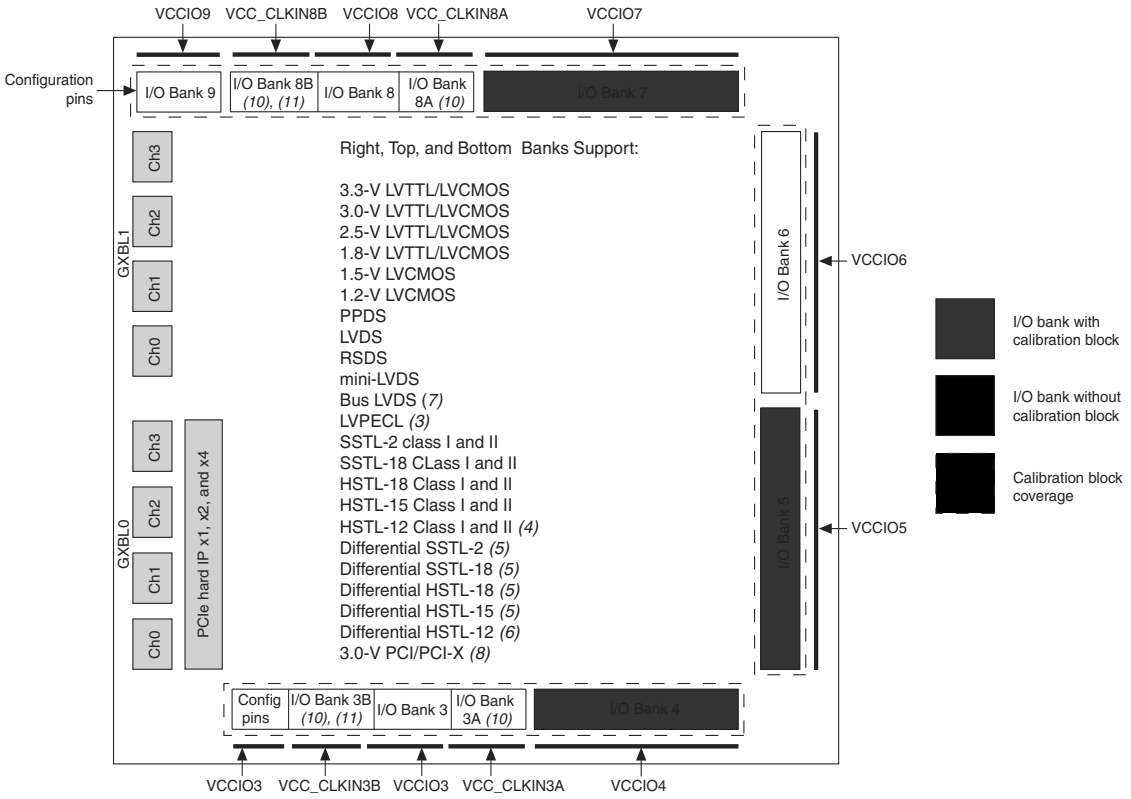
Figure 4–4 shows the embedded multiplier configured to support two 9-bit multipliers.

Figure 4–4. 9-Bit Multiplier Mode



All 9-bit multiplier inputs and results are independently sent through registers. The multiplier inputs can accept signed integers, unsigned integers, or a combination of both. Two 9 × 9 multipliers in the same embedded multiplier block share the same `signa` and `signb` signal. Therefore, all the `Data A` inputs feeding the same embedded multiplier must have the same sign representation. Similarly, all the `Data B` inputs feeding the same embedded multiplier must have the same sign representation.

Figure 6–11. Cyclone IV GX I/O Banks for EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 *(1), (2), (9)*



Notes to Figure 6–11:

(1) This is a top view of the silicon die. For exact pin locations, refer to the pin list and the Quartus II software.

(2) True differential (PPDS, LVDS, mini-LVDS, and RSDS I/O standards) outputs are supported in row I/O banks 5 and 6 only. External resistors are needed for the differential outputs in column I/O banks.

(3) The LVPECL I/O standard is only supported on clock input pins. This I/O standard is not supported on output pins.

(4) The HSTL-12 Class II is supported in column I/O banks 4, 7, and 8.

(5) The differential SSTL-18 and SSTL-2, differential HSTL-18, and HSTL-15 I/O standards are supported only on clock input pins and phase-locked loops (PLLs) output clock pins. PLL output clock pins do not support Class II interface type of differential SSTL-18, HSTL-18, HSTL-15, and HSTL-12 I/O standards.

(6) The differential HSTL-12 I/O standard is only supported on clock input pins and PLL output clock pins. Differential HSTL-12 Class II is supported only in column I/O banks 4, 7, and 8.

(7) BLVDS output uses two single-ended outputs with the second output programmed as inverted. BLVDS input uses the LVDS input buffer.

(8) The PCI-X I/O standard does not meet the IV curve requirement at the linear region.

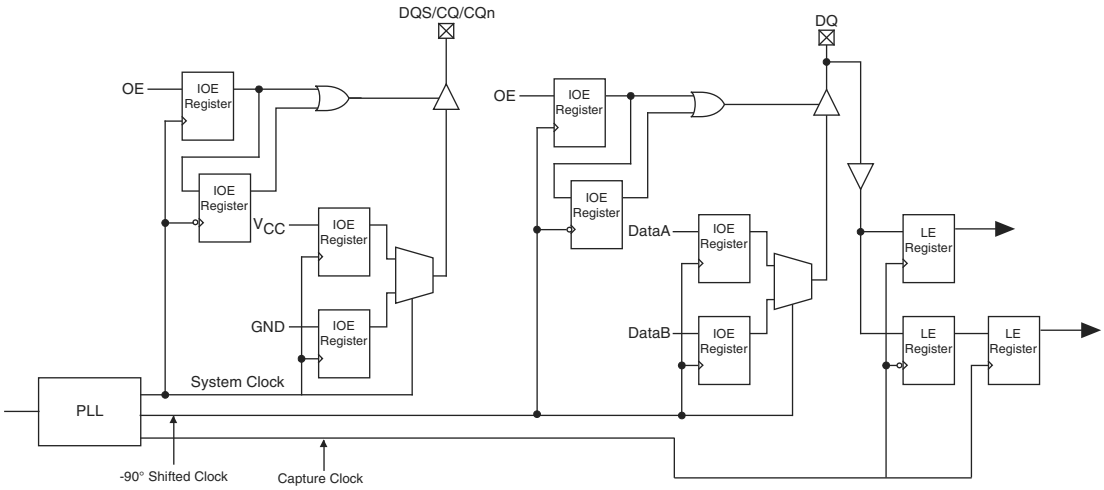
(9) The OCT block is located in the shaded banks 4, 5, and 7.

(10) The dedicated clock input I/O banks 3A, 3B, 8A, and 8B can be used either for HSSI input reference clock pins or clock input pins.

(11) Single-ended clock input support is available for dedicated clock input I/O banks 3B and 8B.

Figure 7–1 shows the block diagram of a typical external memory interface data path in Cyclone IV devices.

Figure 7–1. Cyclone IV Devices External Memory Data Path *(1)*



Note to Figure 7–1:

(1) All clocks shown here are global clocks.

For more information about implementing complete external memory interfaces, refer to the *External Memory Interface Handbook*.

Cyclone IV Devices Memory Interfaces Pin Support

Cyclone IV devices use data (DQ), data strobe (DQS), clock, command, and address pins to interface with external memory. Some memory interfaces use the data mask (DM) or byte write select (BWS#) pins to enable data masking. This section describes how Cyclone IV devices support all these different pins.

For more information about pin utilization, refer to *Volume 2: Device, Pin, and Board Layout Guidelines* of the *External Memory Interface Handbook*.

Data and Data Clock/Strobe Pins

Cyclone IV data pins for external memory interfaces are called D for write data, Q for read data, or DQ for shared read and write data pins. The read-data strobes or read clocks are called DQS pins. Cyclone IV devices support both bidirectional data strobes and unidirectional read clocks. Depending on the external memory standard, the DQ and DQS are bidirectional signals (in DDR2 and DDR SDRAM) or unidirectional signals (in QDR II SRAM). Connect the bidirectional DQ data signals to the same Cyclone IV devices DQ pins. For unidirectional D or Q signals, connect the read-data signals to a group of DQ pins and the write-data signals to a different group of DQ pins.

In QDR II SRAM, the Q read-data group must be placed at a different V_{REF} bank location from the D write-data group, command, or address pins.

devices. The internal oscillator is designed to ensure that its maximum frequency is guaranteed to meet EPCS device specifications. Cyclone IV devices offer the option to select CLKUSR as the external clock source for DCLK. You can change the clock source option in the Quartus II software in the **Configuration** tab of the **Device and Pin Options** dialog box.

EPCS1 does not support Cyclone IV devices because of its insufficient memory capacity.

Table 8–6. AS DCLK Output Frequency

Oscillator	Minimum	Typical	Maximum	Unit
40 MHz	20	30	40	MHz

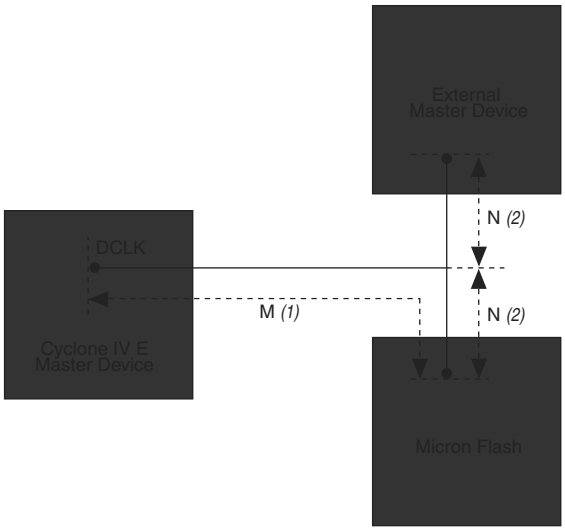
In configuration mode, the Cyclone IV device enables the serial configuration device by driving the nCSO output pin low, which connects to the nCS pin of the configuration device. The Cyclone IV device uses the DCLK and DATA[1] pins to send operation commands and read address signals to the serial configuration device. The configuration device provides data on its DATA pin, which connects to the DATA[0] input of the Cyclone IV device.

All AS configuration pins (DATA[0], DCLK, nCSO, and DATA[1]) have weak internal pull-up resistors that are always active. After configuration, these pins are set as input tri-stated and are driven high by the weak internal pull-up resistors.

The timing parameters for AS mode are not listed here because the t_{CF2CD}, t_{CF2ST0}, t_{CFG}, t_{STATUS}, t_{CF2ST1}, and t_{CD2UM} timing parameters are identical to the timing parameters for PS mode shown in Table 8–12 on page 8–36.

Figure 8–11 shows the recommended balanced star routing for multiple bus master interfaces to minimize signal integrity issues.

Figure 8–11. Balanced Star Routing



Notes to Figure 8–11:

(1) Altera recommends that *M* does not exceed 6 inches, as listed in Table 8–11 on page 8–28.

(2) Altera recommends using a balanced star routing. Keep the *N* length equal and as short as possible to minimize reflection noise from the transmission line. The *M* length is applicable for this setup.

Estimating AP Configuration Time

AP configuration time is dominated by the time it takes to transfer data from the parallel flash to Cyclone IV E devices. This parallel interface is clocked by the Cyclone IV E `DCLK` output (generated from an internal oscillator). The `DCLK` minimum frequency when using the 40-MHz oscillator is 20 MHz (50 ns). In word-wide cascade programming, the `DATA[15..0]` bus transfers a 16-bit word and essentially cuts configuration time to approximately 1/16 of the AS configuration time. Equation 8–4 and Equation 8–5 show the configuration time calculations.

Equation 8–4.

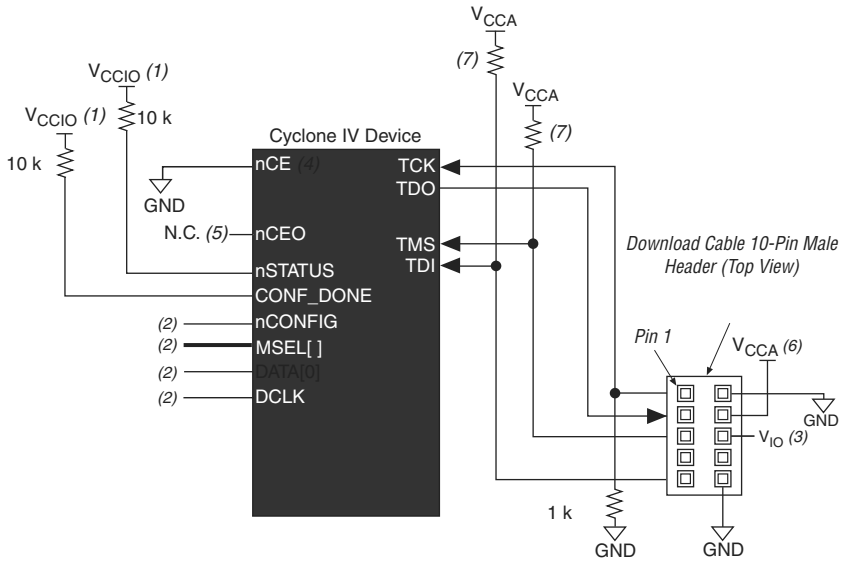
$$\text{Size} \times \left(\frac{\text{maximum DCLK period}}{\text{16 bits per DCLK cycle}} \right) = \text{estimated maximum configuration time}$$

Equation 8–5.

$$9{,}600{,}000 \text{ bits} \times \left(\frac{50 \text{ ns}}{16 \text{ bit}} \right) = 30 \text{ ms}$$

For device using V_{CCIO} of 2.5, 3.0, and 3.3 V, refer to Figure 8–23. All I/O inputs must maintain a maximum AC voltage of 4.1 V because JTAG pins do not have the internal PCI clamping diodes to prevent voltage overshoot when using V_{CCIO} of 2.5, 3.0, and 3.3 V. You must power up the V_{CC} of the download cable with a 2.5-V supply from V_{CCA}. For device using V_{CCIO} of 1.2, 1.5, and 1.8 V, refer to Figure 8–24. You can power up the V_{CC} of the download cable with the supply from V_{CCIO}.

Figure 8–23. JTAG Configuration of a Single Device Using a Download Cable (2.5, 3.0, and 3.3-V V_{CCIO} Powering the JTAG Pins)



Notes to Figure 8–23:

(1) Connect these pull-up resistors to the V_{CCIO} supply of the bank in which the pin resides.

(2) Connect the `nCONFIG` and `MSEL` pins to support a non-JTAG configuration scheme. If you only use JTAG configuration, connect the `nCONFIG` pin to logic-high and the `MSEL` pins to GND. In addition, pull `DCLK` and `DATA[0]` to either high or low, whichever is convenient on your board.

(3) Pin 6 of the header is a V_{IO} reference voltage for the MasterBlaster output driver. V_{IO} must match the device's V_{CCA}. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*. When using the USB-Blaster, ByteBlaster II, ByteBlasterMV, and EthernetBlaster cables, this pin is a no connect.

(4) The `nCE` pin must be connected to GND or driven low for successful JTAG configuration.

(5) The `nCEO` pin is left unconnected or used as a user I/O pin when it does not feed the `nCE` pin of another device.

(6) Power up the V_{CC} of the EthernetBlaster, ByteBlaster II, USB-Blaster, or ByteBlasterMV cable with a 2.5-V supply from V_{CCA}. Third-party programmers must switch to 2.5 V. Pin 4 of the header is a V_{CC} power supply for the MasterBlaster cable. The MasterBlaster cable can receive power from either 5.0- or 3.3-V circuit boards, DC power supply, or 5.0 V from the USB cable. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*.

(7) Resistor value can vary from 1 kΩ to 10 kΩ..

Document Revision History

Table 10–3 lists the revision history for this chapter.

Table 10–3. Document Revision History

Date	Version	Changes
December 2013	1.3	■ Updated the “EXTEST_PULSE” section.
November 2011	1.2	■ Updated the “BST Operation Control” section. ■ Updated Table 10–2.
February 2010	1.1	■ Added Cyclone IV E devices in Table 10–1 and Table 10–2 for the Quartus II software version 9.1 SP1 release. ■ Updated Figure 10–1 and Figure 10–2. ■ Minor text edits.
November 2009	1.0	Initial release.

Table 1–4 lists the synchronization state machine parameters for the word aligner in this mode.

Table 1–4. Synchronization State Machine Parameters

Parameter	Allowed Values
Number of erroneous code groups received to lose synchronization	1–64
Number of continuous good code groups received to reduce the error count by one	1–256

After deassertion of the rx_digitalreset signal in automatic synchronization state machine mode, the word aligner starts looking for the synchronization code groups, word alignment pattern or its complement in the received data stream. When the programmed number of valid synchronization code groups or ordered sets are received, the rx_syncstatus signal is driven high to indicate that synchronization is acquired. The rx_syncstatus signal is constantly driven high until the programmed number of erroneous code groups are received without receiving intermediate good groups; after which the rx_syncstatus signal is driven low. The word aligner indicates loss of synchronization (rx_syncstatus signal remains low) until the programmed number of valid synchronization code groups are received again.

In addition to restoring word boundaries, the word aligner supports the following features:

- Programmable run length violation detection—detects consecutive 1s or 0s in the data stream, and asserts run length violation signal (rx_rlv) when a preset run length threshold (maximum number of consecutive 1s or 0s) is detected. The rx_rlv signal in each channel is clocked by its parallel recovered clock and is asserted for a minimum of two recovered clock cycles to ensure that the FPGA fabric clock can latch the rx_rlv signal reliably because the FPGA fabric clock might have phase differences, ppm differences (in asynchronous systems), or both, with the recovered clock. Table 1–5 lists the run length violation circuit detection capabilities.

Table 1–5. Run Length Violation Circuit Detection Capabilities

Supported Data Width	Detector Range		Increment Step Settings
	Minimum	Maximum	
8-bit	4	128	4
10-bit	5	160	5

Figure 1–45 and Figure 1–46 show the supported transceiver configurations in Basic mode with the 8-bit and 10-bit PMA-PCS interface width respectively.

Figure 1–45. Supported Transceiver Configurations in Basic Mode with the 8-bit PMA-PCS Interface Width

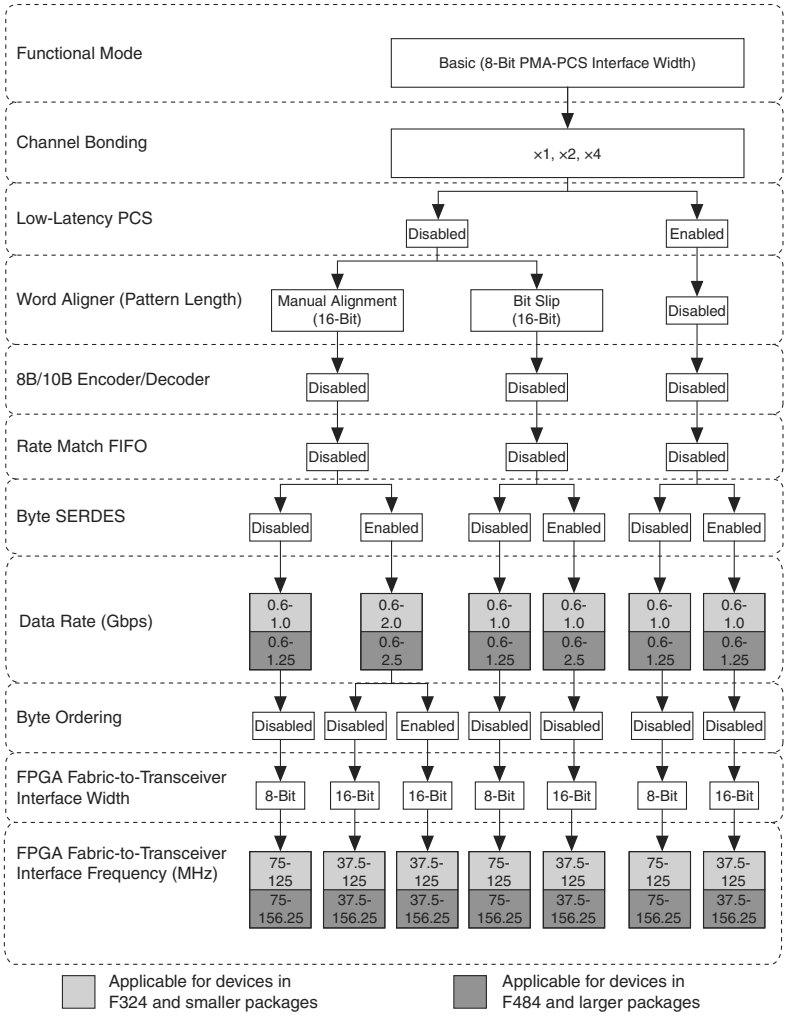
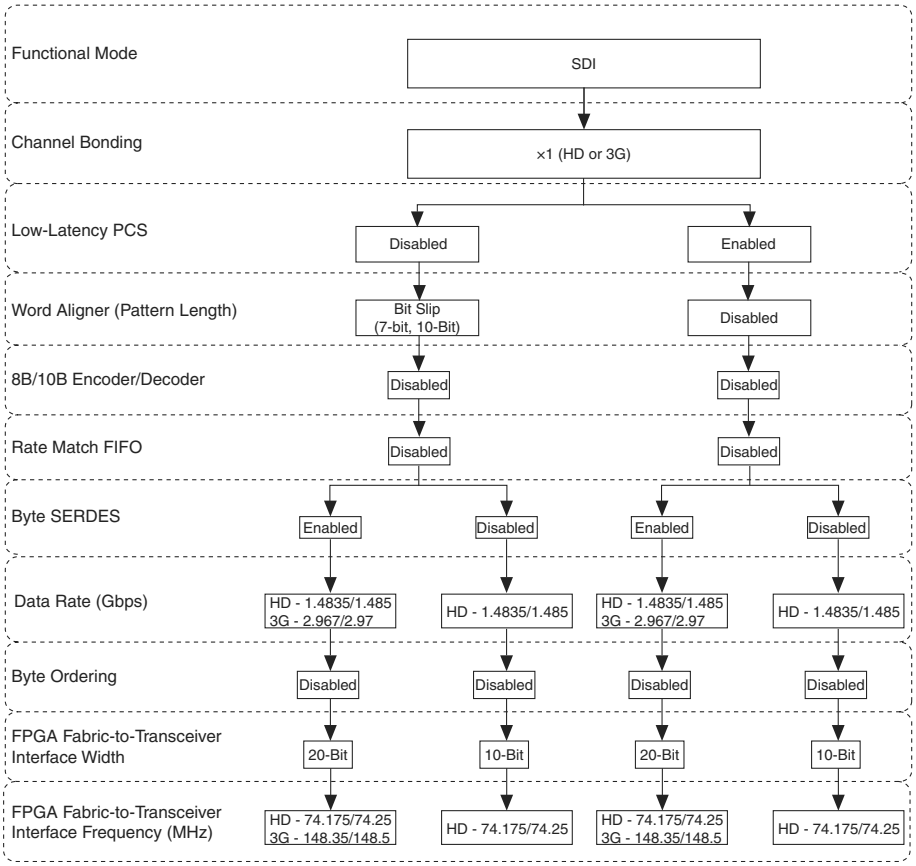


Figure 1–69 shows the transceiver configuration in SDI mode.

Figure 1–69. Transceiver Configuration in SDI Mode



Altera recommends driving `rx_bitslip` port low in configuration where low-latency PCS is not enabled. In SDI systems, the word alignment and framing occurs after de-scrambling, which is implemented in the user logic. The word alignment therefore is not useful, and keeping `rx_bitslip` port low avoids the word aligner from inserting bits in the received data stream.

Loopback

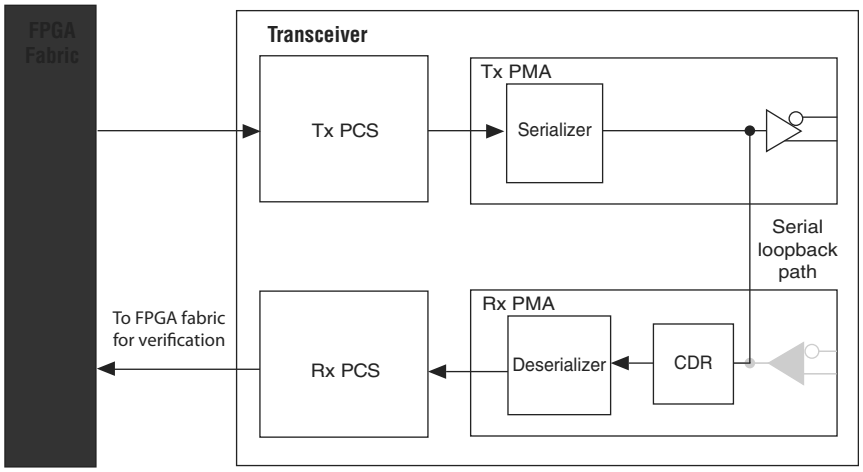
Cyclone IV GX devices provide three loopback options that allow you to verify the operation of different functional blocks in the transceiver channel. The following loopback modes are available:

- reverse parallel loopback (available only for PIPE mode)
- serial loopback (available for all modes except PIPE mode)
- reverse serial loopback (available for all modes except XAUI mode)

In each loopback mode, all transmitter buffer and receiver buffer settings are available if the buffers are active, unless stated otherwise.

Serial loopback mode can only be dynamically enabled or disabled during user mode by performing a dynamic channel reconfiguration.

Figure 1–71. Serial Loopback Path (1)



Note to Figure 1–71:

(1) Grayed-Out Blocks are Not Active in this mode.

Reverse Serial Loopback

The reverse serial loopback mode is available for all functional modes except for XAUI mode. The two reverse serial loopback options from the receiver to the transmitter are:

- Pre-CDR mode where data received through the RX input buffer is looped back to the TX output buffer using the **Reverse serial loopback (pre-CDR)** option
- Post-CDR mode where retimed data through the receiver CDR from the RX input buffer is looped back to the TX output buffer using the **Reverse serial loopback** option

The received data is also available to the FPGA logic. In the transmitter channel, only the transmitter buffer is active.

The transmitter pre-emphasis feature is not available in reverse serial loopback (pre-CDR) mode.

Reverse serial loopback modes can only be dynamically enabled or disabled during user mode by performing a dynamic channel reconfiguration.

Table 1–27. Receiver Ports in ALTGX Megafunction for Cyclone IV GX (Part 3 of 3)

Block	Port Name	Input/ Output	Clock Domain	Description
RX PCS	rx_coreclk	Output	Clock signal	Optional read clock port for the RX phase compensation FIFO.
	rx_phase_comp_fifo_error	Output	Synchronous to `tx_clkout` (non-bonded modes) or `coreclkout` (bonded modes)	RX phase compensation FIFO full or empty indicator. ■ A high level indicates FIFO is either full or empty.
	rx_bitslipboundaryselectout	Output	Asynchronous signal.	Indicate the number of bits slipped in the word aligner configured in manual alignment mode. ■ Values range from 0 to 9.
RX PMA	rx_datain	Input	N/A	Receiver serial data input port.
	rx_freqlocked	Output	Asynchronous signal	Receiver CDR lock state indicator ■ A high level indicates the CDR is in LTD state. ■ A low level indicates the CDR is in LTR state.
	rx_locktodata	Input	Asynchronous signal	Receiver CDR LTD state control signal ■ A high level forces the CDR to LTD state ■ When deasserted, the receiver CDR lock state depends on the `rx_locktorefclk` signal level.
	rx_locktorefclk	Input	Asynchronous signal	Receiver CDR LTR state control signal. ■ The `rx_locktorefclk` and `rx_locktodata` signals control whether the receiver CDR states as follows: [`rx_locktodata:rx_locktorefclk`] ■ 2'b00—receiver CDR is in automatic lock mode ■ 2b'01—receiver CDR is in manual lock mode (LTR state) ■ 2b'1x—receiver CDR is in manual lock mode (LTD state)
	rx_signaldetect	Output	Asynchronous signal	Signal threshold detect indicator. ■ Available in Basic mode when 8B/10B encoder/decoder is used, and in PIPE mode. ■ A high level indicates that the signal present at the receiver input buffer is above the programmed signal detection threshold value.
	rx_recovclkout	Output	Clock signal	CDR low-speed recovered clock ■ Only available in the GIGE mode for applications such as Synchronous Ethernet.

Document Revision History

Table 1–30 lists the revision history for this chapter.

Table 1–30. Document Revision History

Date	Version	Changes
February 2015	3.7	■ Updated the GiGE row in Table 1–14. ■ Updated the "GIGE Mode" section. ■ Updated the note in the "Clock Frequency Compensation" section.
October 2013	3.6	Updated Figure 1–15 and Table 1–4.
May 2013	3.5	Updated Table 1–27 by setting "rx_locktodata" and "rx_locktorefclk" to "Input"
October 2012	3.4	■ Updated the data rate for the V-by-one protocol and the F324 package support in HD-SDI in Table 1–1. ■ Updated note (1) to Figure 1–27. ■ Added latency information to Figure 1–67.
November 2011	3.3	■ Updated "Word Aligner" and "Basic Mode" sections. ■ Updated Figure 1–37.
December 2010	3.2	■ Updated for the Quartus II software version 10.1 release. ■ Updated Table 1–1, Table 1–5, Table 1–11, Table 1–14, Table 1–24, Table 1–25, Table 1–26, Table 1–27, Table 1–28, and Table 1–29. ■ Updated "8B/10B Encoder", "Transmitter Output Buffer", "Receiver Input Buffer", "Clock Data Recovery", "Miscellaneous Transmitter PCS Features", "Miscellaneous Receiver PCS Feature", "Input Reference Clocking", "PCI Express (PIPE) Mode", "Channel Deskewing", "Lane Synchronization", "Serial Loopback", and "Self Test Modes" sections. ■ Added Figure 1–9, Figure 1–10, Figure 1–19, Figure 1–20, and Figure 1–43. ■ Updated Figure 1–53, Figure 1–55, Figure 1–59, Figure 1–60, Figure 1–69, Figure 1–70, Figure 1–71, Figure 1–72, Figure 1–73, and Figure 1–74.
November 2010	3.1	Updated Introductory information.
July 2010	3.0	■ Updated information for the Quartus II software version 10.0 release. ■ Reset control, power down, and dynamic reconfiguration information moved to new *Cyclone IV Reset Control and Power Down* and *Cyclone IV Dynamic Reconfiguration* chapters.

All Supported Functional Modes Except the PCIe Functional Mode

This section describes reset sequences for transceiver channels in bonded and non-bonded configurations. Timing diagrams of some typical configurations are shown to facilitate proper reset sequence implementation. In these functional modes, you can set the receiver CDR either in automatic lock or manual lock mode.

In manual lock mode, the receiver CDR locks to the reference clock (lock-to-reference) or the incoming serial data (lock-to-data), depending on the logic levels on the `rx_locktorefclk` and `rx_locktodata` signals. With the receiver CDR in manual lock mode, you can either configure the transceiver channels in the Cyclone IV GX device in a non-bonded configuration or a bonded configuration. In a bonded configuration, for example in XAUI mode, four channels are bonded together.

Table 2–4 lists the lock-to-reference (LTR) and lock-to-data (LTD) controller lock modes for the `rx_locktorefclk` and `rx_locktodata` signals.

Table 2–4. Lock-To-Reference and Lock-To-Data Modes

rx_locktorefclk	rx_locktodata	LTR/LTD Controller Lock Mode
1	0	Manual, LTR Mode
—	1	Manual, LTD Mode
0	0	Automatic Lock Mode

Bonded Channel Configuration

In a bonded channel configuration, you can reset all the bonded channels simultaneously. Examples of bonded channel configurations are the XAUI, PCIe Gen1 ×2 and ×4, and Basic ×2 and ×4 functional modes. In Basic ×2 and ×4 functional mode, you can bond **Transmitter Only** channels together.

In XAUI mode, the receiver and transmitter channels are bonded. Each of the receiver channels in this mode has its own `rx_freqlocked` output status signals. You must consider the timing of these signals in the reset sequence.

Table 2–5 lists the reset and power-down sequences for bonded configurations under the stated functional modes.

Table 2–5. Reset and Power-Down Sequences for Bonded Channel Configurations

Channel Set Up	Receiver CDR Mode	Refer to
Transmitter Only	Basic ×2 and ×4	"Transmitter Only Channel" on page 2–7
Receiver and Transmitter	Automatic lock mode for XAUI functional mode	"Receiver and Transmitter Channel—Receiver CDR in Automatic Lock Mode" on page 2–8
Receiver and Transmitter	Manual lock mode for XAUI functional mode	"Receiver and Transmitter Channel—Receiver CDR in Manual Lock Mode" on page 2–9

☞ A DC signal is equivalent to 100% duty cycle. For example, a signal that overshoots to 4.3 V can only be at 4.3 V for 65% over the lifetime of the device; for a device lifetime of 10 years, this amounts to 65/10ths of a year.

Table 1–2. Maximum Allowed Overshoot During Transitions over a 10-Year Time Frame for Cyclone IV Devices

Symbol	Parameter	Condition (V)	Overshoot Duration as % of High Time	Unit
V_i	AC Input Voltage	V_I = 4.20	100	%
		V_I = 4.25	98	%
		V_I = 4.30	65	%
		V_I = 4.35	43	%
		V_I = 4.40	29	%
		V_I = 4.45	20	%
		V_I = 4.50	13	%
		V_I = 4.55	9	%
		V_I = 4.60	6	%

Figure 1–1 shows the methodology to determine the overshoot duration. The overshoot voltage is shown in red and is present on the input pin of the Cyclone IV device at over 4.3 V but below 4.4 V. From Table 1–2, for an overshoot of 4.3 V, the percentage of high time for the overshoot can be as high as 65% over a 10-year period. Percentage of high time is calculated as ([delta T]/T) × 100. This 10-year period assumes that the device is always turned on with 100% I/O toggle rate and 50% duty cycle signal. For lower I/O toggle rates and situations in which the device is in an idle state, lifetimes are increased.

Figure 1–1. Cyclone IV Devices Overshoot Duration

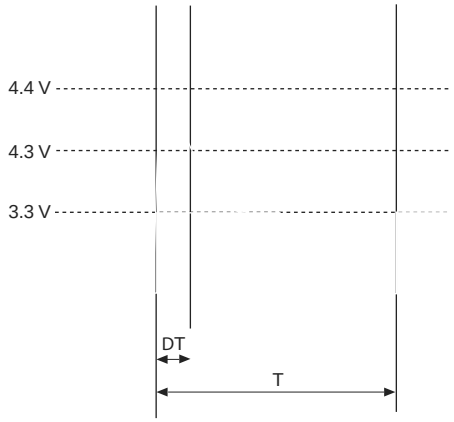


Table 1–21. Transceiver Specification for Cyclone IV GX Devices (Part 2 of 4)

Symbol/ Description	Conditions	C6			C7, I7			C8			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Receiver											
Supported I/O Standards	1.4 V PCML, 1.5 V PCML, 2.5 V PCML, LVPECL, LVDS										
Data rate (F324 and smaller package) (15)	—	600	—	2500	600	—	2500	600	—	2500	Mbps
Data rate (F484 and larger package) (15)	—	600	—	3125	600	—	3125	600	—	2500	Mbps
Absolute V_{MAX} for a receiver pin (3)	—	—	—	1.6	—	—	1.6	—	—	1.6	V
Operational V_{MAX} for a receiver pin	—	—	—	1.5	—	—	1.5	—	—	1.5	V
Absolute V_{MIN} for a receiver pin	—	–0.4	—	—	–0.4	—	—	–0.4	—	—	V
Peak-to-peak differential input voltage V_{ID} (diff p-p)	V_{ICM} = 0.82 V setting, Data Rate = 600 Mbps to 3.125 Gbps	0.1	—	2.7	0.1	—	2.7	0.1	—	2.7	V
V_{ICM}	V_{ICM} = 0.82 V setting	—	820 ± 10%	—	—	820 ± 10%	—	—	820 ± 10%	—	mV
Differential on-chip termination resistors	100–Ω setting	—	100	—	—	100	—	—	100	—	Ω
	150–Ω setting	—	150	—	—	150	—	—	150	—	Ω
Differential and common mode return loss	PIPE, Serial Rapid I/O SR, SATA, CPRI LV, SDI, XAUI	Compliant									—
Programmable ppm detector (4)	—	± 62.5, 100, 125, 200, 250, 300									ppm
Clock data recovery (CDR) ppm tolerance (without spread-spectrum clocking enabled)	—	—	—	±300 (5), ±350 (6), (7)	—	—	±300 (5), ±350 (6), (7)	—	—	±300 (5), ±350 (6), (7)	ppm
CDR ppm tolerance (with synchronous spread-spectrum clocking enabled) (8)	—	—	—	350 to –5350 (7), (9)	—	—	350 to –5350 (7), (9)	—	—	350 to –5350 (7), (9)	ppm
Run length	—	—	80	—	—	80	—	—	80	—	UI
Programmable equalization	No Equalization	—	—	1.5	—	—	1.5	—	—	1.5	dB
	Medium Low	—	—	4.5	—	—	4.5	—	—	4.5	dB
	Medium High	—	—	5.5	—	—	5.5	—	—	5.5	dB
	High	—	—	7	—	—	7	—	—	7	dB